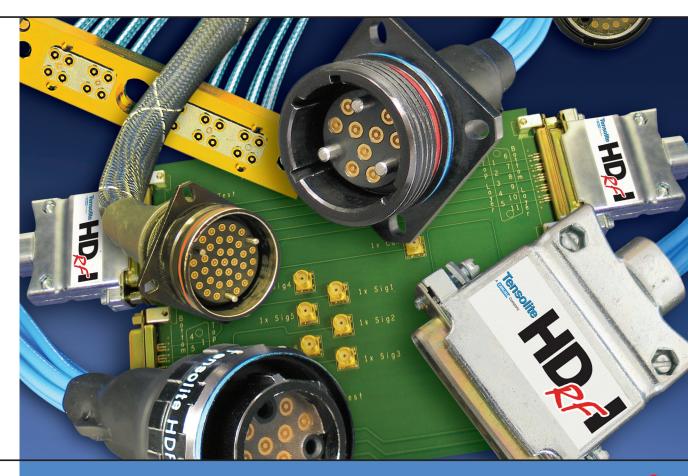
HDRFI[™] Series

Tensolite High-Performance Cable & Interconnect Systems









HDRFI[™] is a patented Tensolite connection system that transfers high frequency signals through a unique planar interface. This planar interface removes the need for typical pin and socket connections by utilizing a z-axis elastomer to provide the electrical path between the mated connectors. The elastomer is made up of silicone, impregnated with gold plated stainless steel wires and is arranged on a .035mm pitch. When compressed by the mating halves, the gold plated wires mechanically connect the two planar surfaces and creates an electrical EMI barrier to provide excellent isolation.

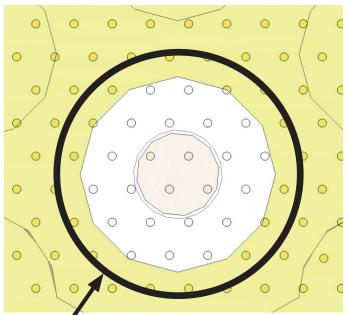
HDRFI[™] is available only as an assembly in three product line offerings: D-Sub, RF Circular and custom applications. The assemblies can be used with a 26AWG coax for internal applications or 24AWG for external requirements. Consult factory for more information.

Features / Benefits

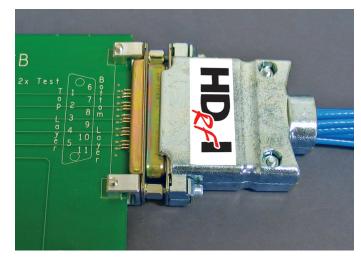
- High Bandwidth
- High Density
- Small Form Factor
- Center to Center spacing 0.130"
- Eliminates Stubbing
- Alignment of the connector is not made through the RF path
- Can be used differentially or single ended







Effective Electrical Outer Conductor





RF D-Sub

The RF D-Sub connector family is available in four different shell sizes and can be used in cable to cable, cable to board or board to board applications. Designed with high performance in mind, the insert arrangements are maximized to hold more impedance controlled size 16 type RF contacts than any other D-sub connector on the market today. The HDRFI™ RF contacts are press-in style and the connectors can accommodate standard D-sub backshells and mounting hardware.

RF Circular

The RF Circular connector family is designed for high performance applications. The insert arrangements are maximized to hold more impedance controlled size 16 type RF contacts than any other circular connector on the market today. The product line consists of shell sizes 15 – 25 and are based on the D38999 specification. The HDRFI[™] RF contacts are press-in style and the connectors can accommodate standard D38999 backshells and hardware.

RF Circular – Mixed Signal

The RF Circular – Mixed Signal connector family is a perfect solution to combine both power and high frequency RF contacts into the same connector body. The product line consists of shell sizes 15 – 25 and are based on the D38999 specification. The signal pins are size 20, rated to 7 amps and are combined with the HDRFI[™] RF contacts. All of the contacts are press-in style and the connectors can accommodate standard D38999 backshells and hardware.

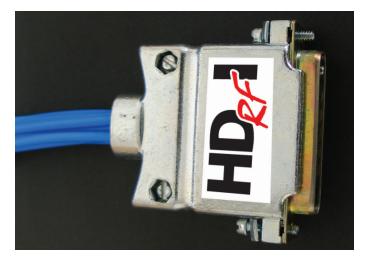
Custom Applications

HDRFI[™] can be customized to fit almost any application. From custom board connectors, to insert arrangements that can have a common ground plane, to having each signal path isolated from each other.



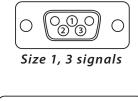


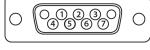
RF-DSUB Series



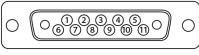


Mating Face View

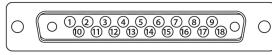




Size 2, 7 signals



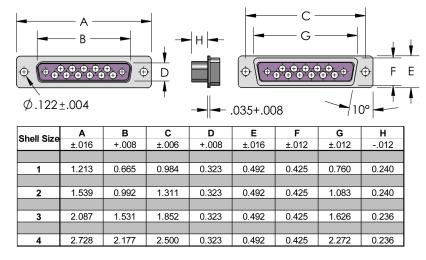
Size 3, 11 signals



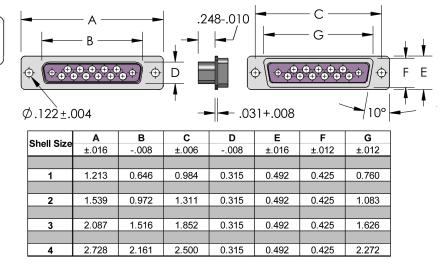
Size 4, 18 signals



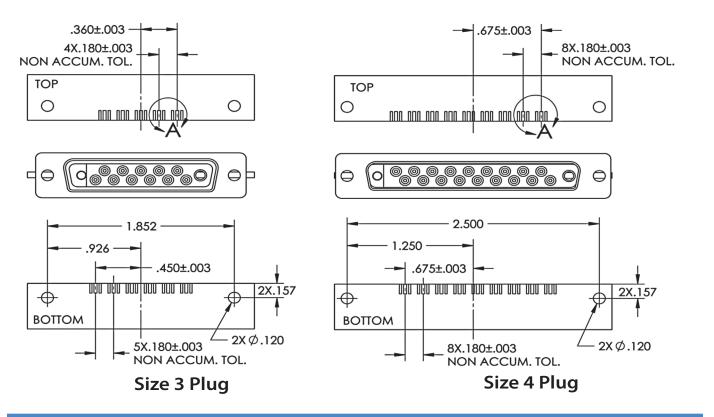
Size 3 Data Plug (shown)



Size 3 Data Receptacle (shown)



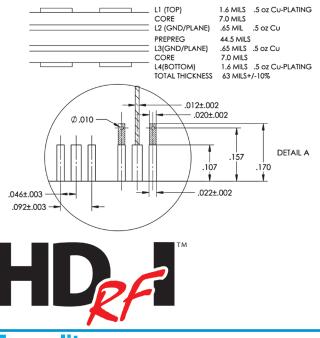
High Density RF Interconnect RF D-Sub



NOTES: SUGGESTED PAD LAYOUT FOR MICROSTRIP LINE BOARD MATERIAL SHALL BE FR4 OR EQUIVALENT. DIELECTRIC CONSTANT = 4.0 TANGENT LOSS = .021 1.

- DIELECTRIC CONSTANT = 4.0 TANGENT LOSS = .021 SOLDERMASK SHALL BE LIQUID PHOTO IMAGEABLE (LPI) BOTH SIDES OVER BARE COPPER. THICKNESS = 35 MicroMeters +/-0.5 MicroMeter. LAYER(1) TOP AND LAYER4(BOTTOM) ARE THE CONTROLLED IMPEDANCE BOARD (SIGNAL LINE: 50 Ohm +/-5% (LINE WIDTH 11.5 MILS.) BOARD STACK-UP AND VIA STRUCTURE. 2.
- 3.
- 4

A CARLISLE Company

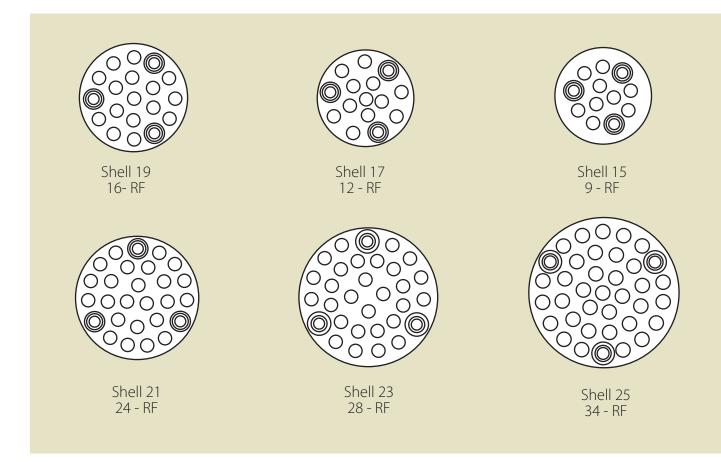


 \oplus (+)- .100 .253

The RF D-Sub product can be launched in an edge mount configuration, as shown above, or vertically. Consult factory for vertical PCB layouts.

High Density RF Interconnect *RF Circular*

Insert Arrangements - RF

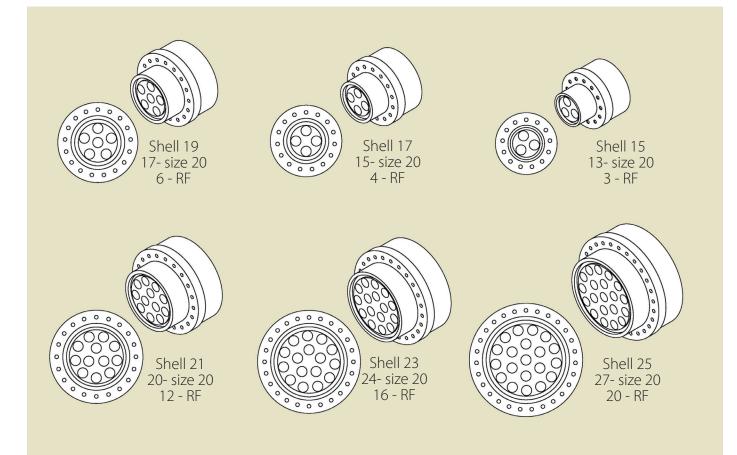




RF Circular—Mixed Signal

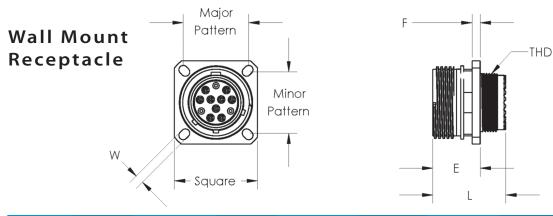


Insert Arrangements - MS





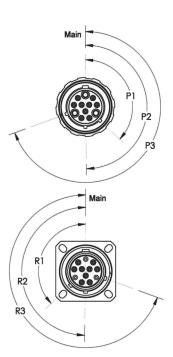
RF Circular



Shell Size	Square	Pattern Major	Pattern Minor	W	THD	L	F	E	Panel Hole +.005
15	1.230	.970	.906	.125	M22 x 1.0	1.080	.120	.700	1.005
17	1.312	1.062	.970	.125	M25 x 1.0	1.080	.120	.700	1.195
19	1.437	1.156	1.062	.125	M28 x 1.0	1.080	.120	.700	1.255
21	1.562	1.250	1.156	.125	M31 x 1.0	1.080	.120	.700	1.380
23	1.688	1.375	1.250	.125	M34 x 1.0	1.080	.120	.700	1.515
25	1.812	1.500	1.375	.125	M37 x 1.0	1.080	.120	.700	1.630

Keying Options

MATING VIEW						
Key / Angle						
(cw from 12:00)	Main	P1	P2	P3		
Normal	0	133	180	250		
А	0	135	180	225		
В	0	95	180	212		
С	0	100	155	200		
D	0	75	155	200		
E	0	30	155	280		





RF Circular Connector Part Numbering

HDRFI/ 10 A 21 MS N Shell Style Service Class Shell Size Insert Style Keying Option

Shell Style:

- 10 Wall Mount Receptacle
- 20 Straight Plug
- 30 Jam Nut Receptacle

Service Class:

- A Cadmium per QQ-P-416F Type 2, Class 2
- B Black Anodize per Mil-A-8625 Type II, .4 mil
- C Electroless Nickel per ASTM 733-90 SC2, Type 1, Class 5

Shell Size:

15 - 17 - 19 - 21 - 23 - 25

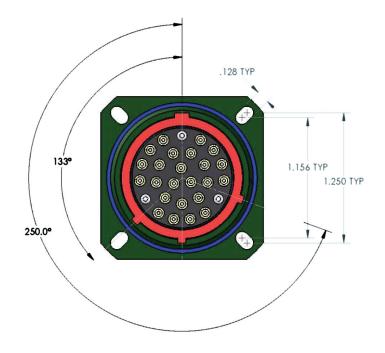
Insert Style:

RF – Loaded w/ RF contacts only MS – Mixed Signal

Keying Options:

See page 8 for keying options



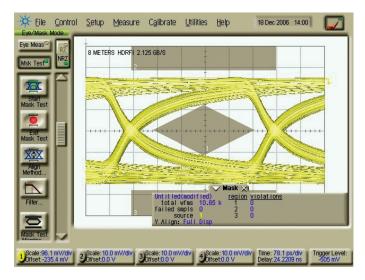


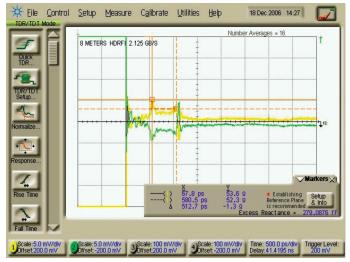


Electrical Performance

Digital Applications

The eye pattern data is based on the Double Speed Fibre Channel protocol at 8 meters long without equalization using Tensolite HFF-1087 cable. The HDRFI™ coax contacts were set as a differential signal in a RF D-Sub shell size 2.

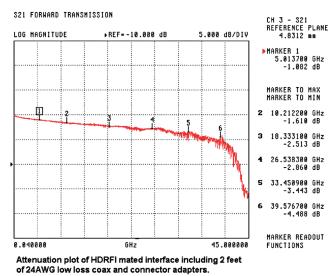


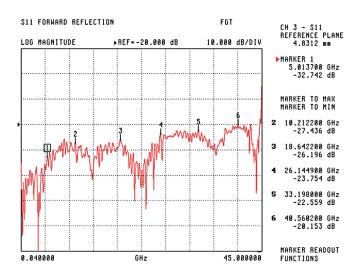




RF Applications

The test below is the typical RF performance of an HDRFI[™] assembly to 40GHz. The configuration includes a mated pair of Tensolite's HDRFI[™] coax connectors with Tensolite HFF-1087 cable and SMP connectors at the ends that attach to the test leads.





Specifications

Mechanical					
On-Center Sp	pacing	0.130" Center to Center Minimum			
Mating/Com	pression Force	1.5 Lbs / Contact			
Durability		2,000 Mating Cycles			
Operating Te	mperature	-20°C to +120°C			
Electrical					
Insulation Re	esistance	100 Megohms Minimum			
Dielectric Wi	thstand Voltage	1,000 Vrms @ Sea Level			
Current Ratin	ng @ 70°C	1.0 Amp			
Contact Resi	stance (max)	150mOhms			
Impedance,	Nominal	50Ω			
CW Power Ra	iting (max)	20 Watts			
Frequency R	ange	to 40GHz			
Insertion Los	ss (mated pair)	0.25dB @ 40GHz			
VSWR (max)					
Up to 4	4 GHz	1.18			
4 – 12	GHz	1.25			
12 – 18	3 GHz	1.35			
18 – 26 GHz		1.40			
26 - 40) GHz	1.45			
Environmenta	l				
Mechanical Shock	EIA 364, Test #27	70 G's, 10 Milisecond, 1/2 sine, 5 cycles			
Random Vibration	EIA 364, Test #28	8.8 G's RMS, 50 to 2k hz, 1 hr/axis, 3 axis			
Mixed Flowing Gas EIA 364, Test #65 C1 ₂ SO ₂ 100 ppb, exposure 2		C1 ₂ 10 ppb, NO ₂ 200 ppb, H ₂ S 10 ppb, ure 20 days, mated			
		55°C to 150°C, 5 cycles, mated			
Humidity EIA 364 Test #31 25°C to (Thermal Cycling) 500 hours, mated		5°C to 65°C @ 90 to 95% R.H., continuous			
Temperature Life EIA 364 Test #17 12		20°C, 500 hours 1.0 Amp, mated			







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For more information please e-mail hdrfi@CarlisleIT.com



HDRFI™ products are covered by patent number 7,074,047 and others. HDRFI™ is a trademark of the Tensolite Company.